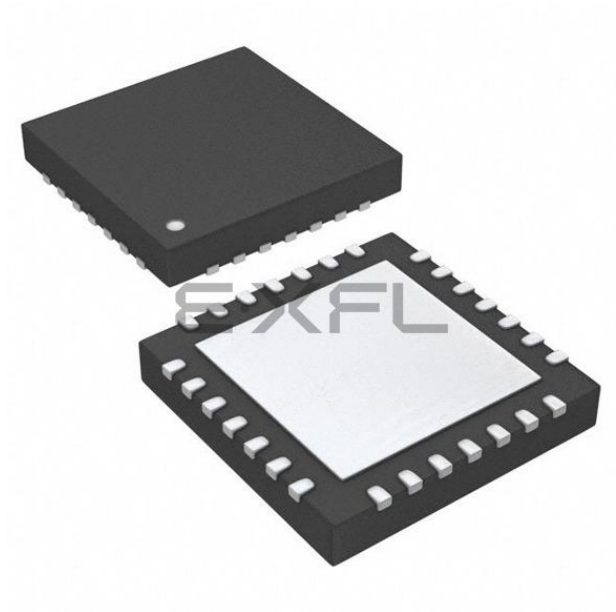

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1902-e-mv

3.2.6 CORE FUNCTION REGISTERS SUMMARY

The Core Function registers listed in Table 3-4 can be addressed from any Bank.

TABLE 3-4: CORE FUNCTION REGISTERS SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 0-31											
x00h or x80h	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
x01h or x81h	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
x02h or x82h	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
x03h or x83h	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
x04h or x84h	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
x05h or x85h	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
x06h or x86h	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
x07h or x87h	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
x08h or x88h	BSR	—	—	—	BSR4	BSR3	BSR2	BSR1	BSR0	---0 0000	---0 0000
x09h or x89h	WREG	Working Register								0000 0000	uuuu uuuu
x0Ah or x8Ah	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
x0Bh or x8Bh	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 0											
00Ch	PORTA	PORTA Data Latch when written: PORTA pins when read								xxxx xxxx	uuuu uuuu
00Dh	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
00Eh	PORTC	PORTC Data Latch when written: PORTC pins when read								xxxx xxxx	uuuu uuuu
00Fh	—	Unimplemented								—	—
010h	PORTE	—	—	—	—	RE3	—	—	—	---- x---	---- u---
011h	PIR1	TMR1GIF	ADIF	—	—		—	—	TMR1IF	00-- ---0	0000 ---0
012h	PIR2	—	—	—	—	—	LCDIF	—	—	---- -0--	---- -0--
013h	—	Unimplemented								—	—
014h	—	Unimplemented								—	—
015h	TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
016h	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
017h	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
018h	T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	0000 00-0	uuuu uu-u
019h	T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	0000 0x00	uuuu uxuu
01Ah to 01Fh	—	Unimplemented								—	—
Bank 1											
08Ch	TRISA	PORTA Data Direction Register								1111 1111	1111 1111
08Dh	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
08Eh	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
08Fh	—	Unimplemented								—	—
090h	TRISE	—	—	—	—	—(2)	—	—	—	---- 1---	---- 1---
091h	PIE1	TMR1GIE	ADIE	—	—	—	—	—	TMR1IE	00-- ---0	0000 ---0
092h	PIE2	—	—	—	—	—	LCDIE	—	—	---- -0--	---- -0--
093h	—	Unimplemented								—	—
094h	—	Unimplemented								—	—
095h	OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
096h	PCON	STKOVF	STKUNF	—	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	00-1 11qq	qq-q qquu
097h	WDTCON	—	—	WDTPS4	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN	--01 0110	--01 0110
098h	—	Unimplemented								—	—
099h	OSCCON	—	IRCF3	IRCF2	IRCF1	IRCF0	—	SCS1	SCS0	-011 1-00	-011 1-00
09Ah	OSCSTAT	T1OSCR	—	OSTS	HFIOFR	—	—	LFIOFR	HFIOFS	0-q0 --00	q-qq --0q
09Bh	ADRESL	A/D Result Register Low								xxxx xxxx	uuuu uuuu
09Ch	ADRESH	A/D Result Register High								xxxx xxxx	uuuu uuuu
09Dh	ADCON0	—	CHS4	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	-000 0000	-000 0000
09Eh	ADCON1	ADFM	ADCS2	ADCS1	ADCS0	—	—	ADPREF1	ADPREF0	0000 ----	0000 ----
09Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

TABLE 3-5: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 15 (Continued)											
7ABh	—	Unimplemented								—	—
7ACh	LCDDATA12	—	—	—	—	—	SEG26 COM0	SEG25 COM0	SEG24 COM0	---- -xxx	---- -uuu
7ADh	—	Unimplemented								—	—
7AEh	—	Unimplemented								—	—
7AFh	LCDDATA15	—	—	—	—	—	SEG26 COM1	SEG25 COM1	SEG24 COM1	---- -xxx	---- -uuu
7B0h	—	Unimplemented								—	—
7B1h	—	Unimplemented								—	—
7B2h	LCDDATA18	—	—	—	—	—	SEG26 COM2	SEG25 COM2	SEG24 COM2	---- -xxx	---- -uuu
7B3h	—	Unimplemented								—	—
7B4h	—	Unimplemented								—	—
7B5h	LCDDATA21	—	—	—	—	—	SEG26 COM3	SEG25 COM3	SEG24 COM3	---- -xxx	---- -uuu
7B6h — 7EFh	—	Unimplemented								—	—
Bank 16-30											
x0Ch or x8Ch to x1Fh or x9Fh	—	Unimplemented								—	—
Bank 31											
F8Ch — FE3h	—	Unimplemented								—	—
FE4h	STATUS_SHAD	—	—	—	—	—	Z_SHAD	DC_SHAD	C_SHAD	---- -xxx	---- -uuu
FE5h	WREG_SHAD	Working Register Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_SHAD	—	—	—	Bank Select Register Normal (Non-ICD) Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_SHAD	—	Program Counter Latch High Register Normal (Non-ICD) Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_SHAD	Indirect Data Memory Address 0 Low Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_SHAD	Indirect Data Memory Address 0 High Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_SHAD	Indirect Data Memory Address 1 Low Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_SHAD	Indirect Data Memory Address 1 High Pointer Normal (Non-ICD) Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top of Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top of Stack High byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: Unimplemented, read as '1'.

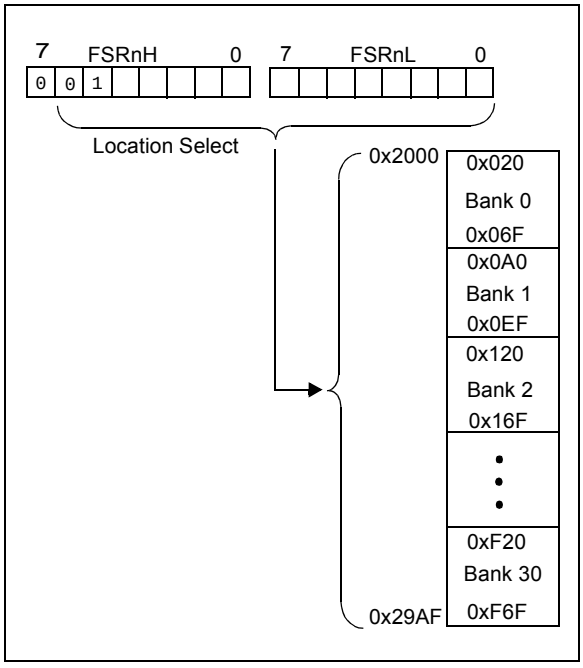
3.5.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

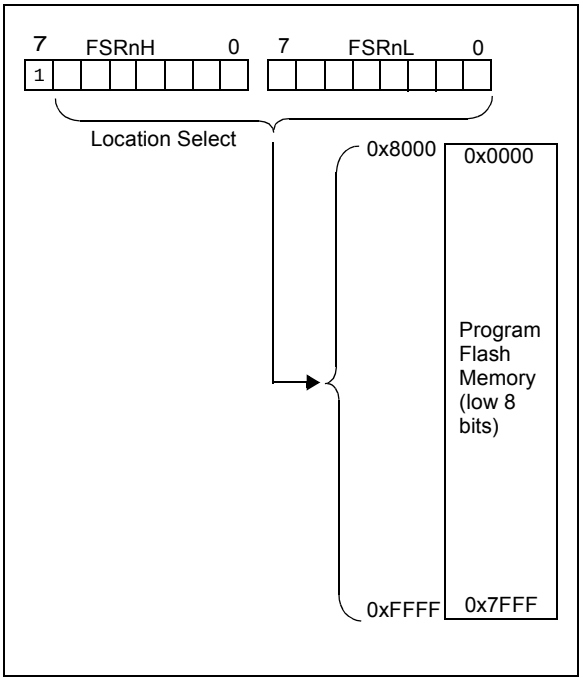
FIGURE 3-11: LINEAR DATA MEMORY MAP



3.5.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-12: PROGRAM FLASH MEMORY MAP

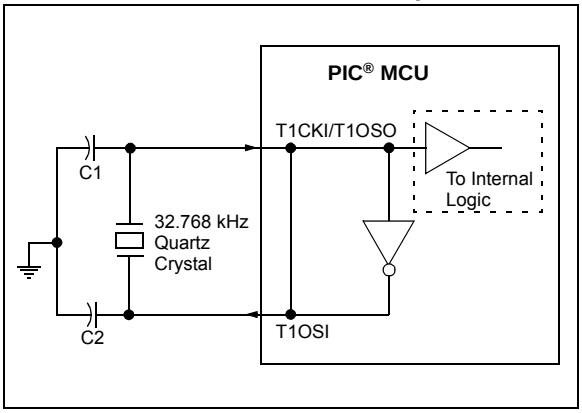


6.2.1.2 Secondary Oscillator

The secondary oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1CKI/T1OSO and T1OSI device pins.

The secondary oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 6.3 "Clock Switching"** for more information.

FIGURE 6-3: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)
- TB097, "*Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS*" (DS91097)
- AN1288, "*Design Practices for Low-Power External Oscillators*" (DS01288)

6.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<1:0> bits in Configuration Word 1 to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 6.3 "Clock Switching"**for more information.

In **INTOSC** mode, CLKIN is available for general purpose I/O. CLKOUT is available for general purpose I/O or CLKOUT.

The function of the CLKOUT pin is determined by the state of the $\overline{\text{CLKOUTEN}}$ bit in Configuration Word 1.

The internal oscillator block has two independent oscillators that provides the internal system clock source.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz.
2. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

6.2.2.1 HFINTOSC

The High-Frequency Internal Oscillator (HFINTOSC) is a factory calibrated 16 MHz internal clock source.

The output of the HFINTOSC connects to a postscaler and multiplexer (see Figure 6-1). The frequency derived from the HFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 6.2.2.4 "Internal Oscillator Clock Switch Timing"** for more information.

The HFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<1:0> = 11, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'.

The High-Frequency Internal Oscillator Ready bit (HFIOFR) of the OSCSTAT register indicates when the HFINTOSC is running and can be utilized.

The High-Frequency Internal Oscillator Status Stable bit (HFIOFS) of the OSCSTAT register indicates when the HFINTOSC is running within 0.5% of its final value.

7.0 INTERRUPTS

The interrupt feature allows certain events to preempt normal program flow. Firmware is used to determine the source of the interrupt and act accordingly. Some interrupts can be configured to wake the MCU from Sleep mode.

This chapter contains the following information for Interrupts:

- Operation
- Interrupt Latency
- Interrupts During Sleep
- INT Pin
- Automatic Context Saving

Many peripherals produce Interrupts. Refer to the corresponding chapters for details.

A block diagram of the interrupt logic is shown in Figure 7.1 and Figure 7.1.

FIGURE 7-1: INTERRUPT LOGIC

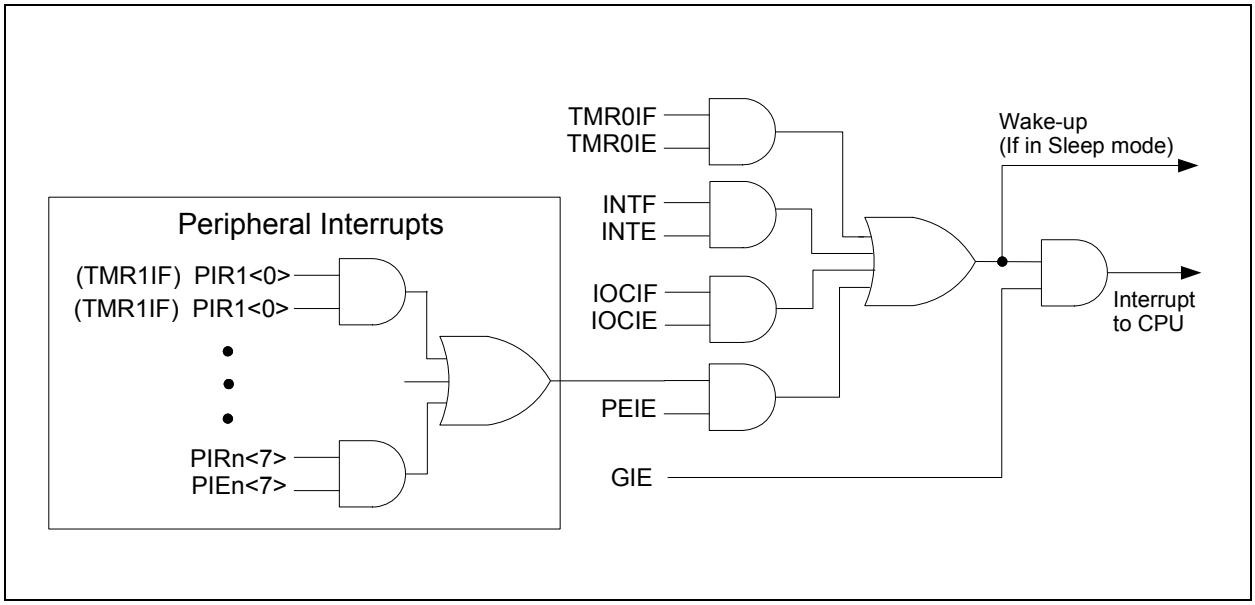


TABLE 7-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	60
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			121
PIE1	TMR1GIE	ADIE	—	—	—	—	—	TMR1IE	61
PIE2	—	—	—	—	—	LCDIE	—	—	62
PIR1	TMR1GIF	ADIF	—	—	—	—	—	TMR1IF	63
PIR2	—	—	—	—	—	LCDIF	—	—	64

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupts.

8.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Secondary oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Secondary oscillator

I/O pins that are high-impedance inputs should be pulled to VDD or VSS externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include the FVR module. See **13.0 "Fixed Voltage Reference (FVR)"** for more information.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 5.11, Determining the Cause of a Reset**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

TABLE 10-1: FLASH MEMORY ORGANIZATION BY DEVICE

Device	Row Erase (words)	Write Latches (words)
PIC16(L)F1902	32	32
PIC16(L)F1903		

10.2.1 READING THE FLASH PROGRAM MEMORY

To read a program memory location, the user must:

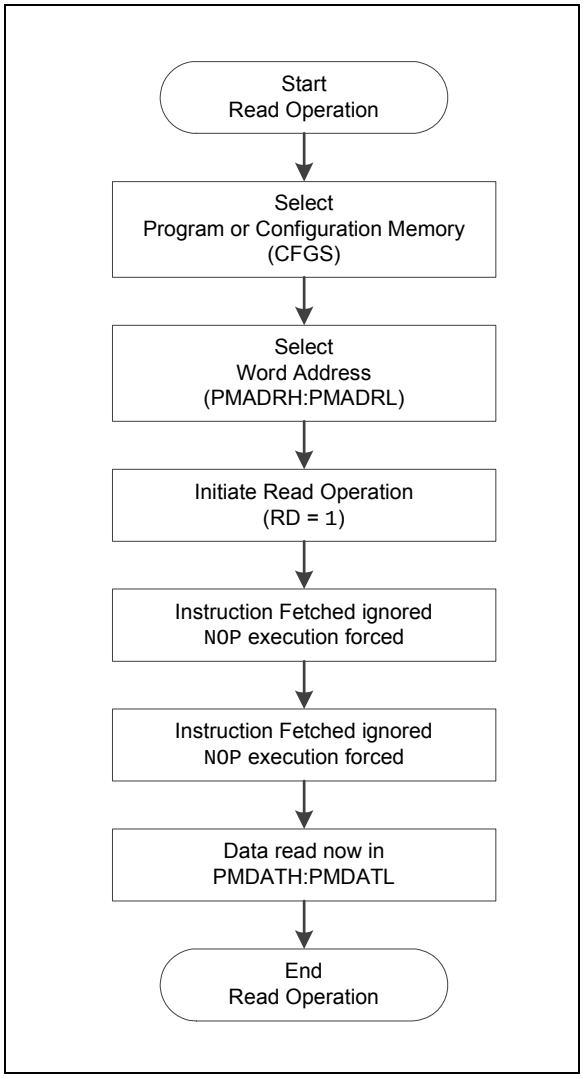
1. Write the desired address to the PMADRH:PMADRL register pair.
2. Clear the CFGS bit of the PMCON1 register.
3. Then, set control bit RD of the PMCON1 register.

Once the read control bit is set, the program memory Flash controller will use the second instruction cycle to read the data. This causes the second instruction immediately following the "`BSF PMCON1,RD`" instruction to be ignored. The data is available in the very next cycle, in the PMDATH:PMDATL register pair; therefore, it can be read as two bytes in the following instructions.

PMDATH:PMDATL register pair will hold this value until another read or until it is written to by the user.

Note:	The two instructions following a program memory read are required to be `NOP`s. This prevents the user from executing a 2-cycle instruction on the next instruction after the RD bit is set.

FIGURE 10-1: FLASH PROGRAM MEMORY READ FLOWCHART



EXAMPLE 10-2: ERASING ONE ROW OF PROGRAM MEMORY

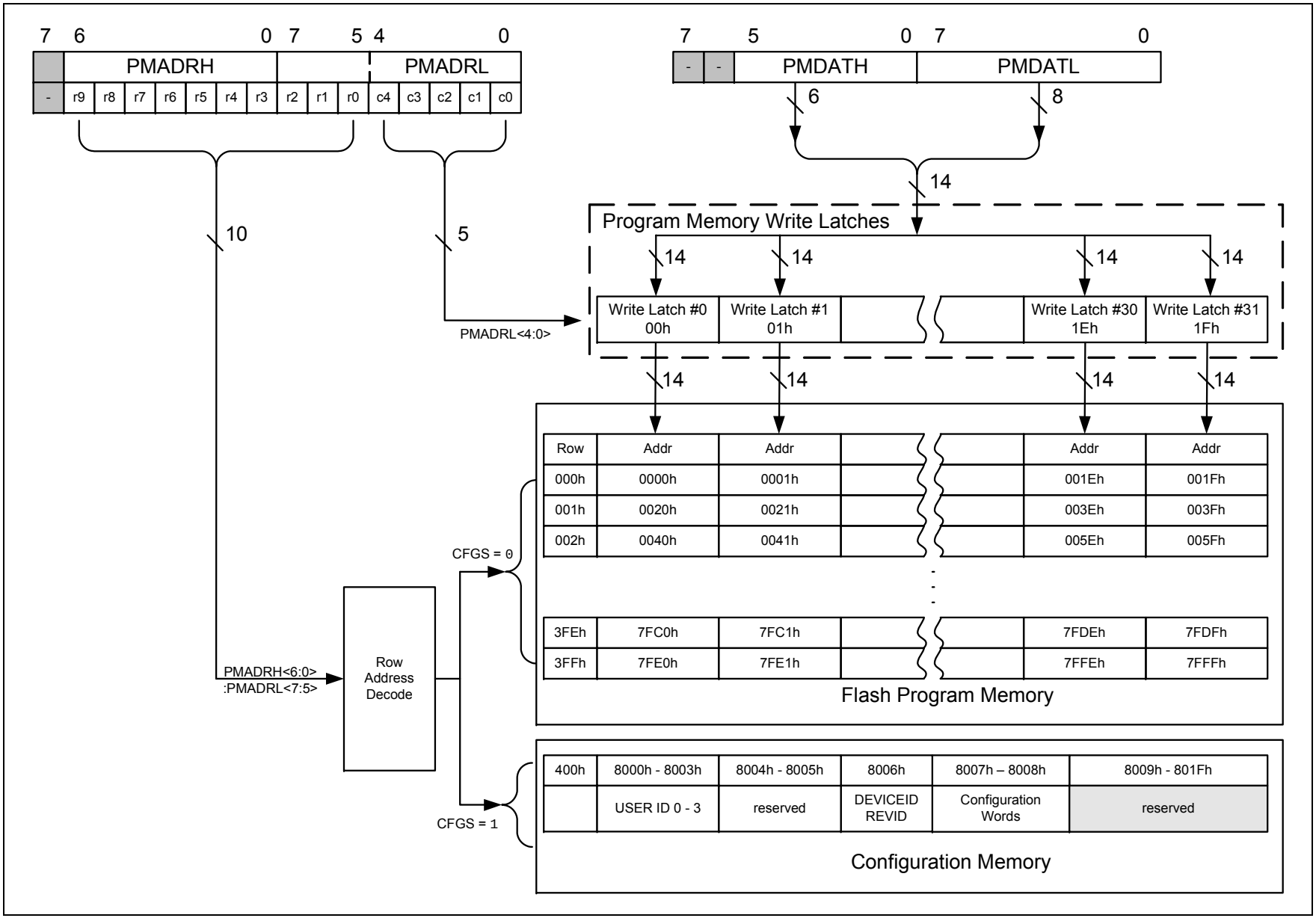
```
; This row erase routine assumes the following:
; 1. A valid address within the erase row is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       PMADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       PMADRH
        BCF         PMCON1,CFGS     ; Not configuration space
        BSF         PMCON1,FREE     ; Specify an erase operation
        BSF         PMCON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       PMCON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       PMCON2          ; Write AAh
        BSF         PMCON1,WR       ; Set WR bit to begin erase
        NOP                         ; NOP instructions are forced as processor starts
        NOP                         ; row erase of program memory.
                                    ;
                                    ; The processor stalls until the erase process is complete
                                    ; after erase processor continues with 3rd instruction

        BCF         PMCON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

FIGURE 10-5: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES



REGISTER 11-5: PORTB: PORTB REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RB<7:0>**: PORTB General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

REGISTER 11-6: TRISB: PORTB TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISB<7:0>:** PORTB Tri-State Control bits
1 = PORTB pin configured as an input (tri-stated)
0 = PORTB pin configured as an output

REGISTER 11-7: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATB<7:0>**: PORTB Output Latch Value bits(1)

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are up to 11 channel selections available:

- AN<13:0> pins
- Temperature Indicator
- FVR (Fixed Voltage Reference) Output

Refer to **Section 13.0 "Fixed Voltage Reference (FVR)"** and **Section 14.0 "Temperature Indicator Module"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- V_{REF}+ pin
- V_{DD}

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- F_{RC} (dedicated internal oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 15-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the A/D conversion requirements in **Section 21.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the F_{RC}, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

REGISTER 15-3: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<9:2>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<9:2>**: ADC Result Register bits
Upper eight bits of 10-bit conversion result

REGISTER 15-4: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<1:0>		—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **ADRES<1:0>**: ADC Result Register bits
Lower two bits of 10-bit conversion result

bit 5-0 **Reserved**: Do not use.

17.6.2.1 T1G Pin Gate Operation

The T1G pin is one source for Timer1 gate control. It can be used to supply an external source to the Timer1 gate circuitry.

17.6.2.2 Timer0 Overflow Gate Operation

When Timer0 increments from FFh to 00h, a low-to-high pulse will automatically be generated and internally supplied to the Timer1 gate circuitry.

17.6.3 TIMER1 GATE TOGGLE MODE

When Timer1 Gate Toggle mode is enabled, it is possible to measure the full-cycle length of a Timer1 gate signal, as opposed to the duration of a single level pulse.

The Timer1 gate source is routed through a flip-flop that changes state on every incrementing edge of the signal. See Figure 17-4 for timing details.

Timer1 Gate Toggle mode is enabled by setting the T1GTM bit of the T1GCON register. When the T1GTM bit is cleared, the flip-flop is cleared and held clear. This is necessary in order to control which edge is measured.

Note:	Enabling Toggle mode at the same time as changing the gate polarity may result in indeterminate operation.

17.6.4 TIMER1 GATE SINGLE-PULSE MODE

When Timer1 Gate Single-Pulse mode is enabled, it is possible to capture a single pulse gate event. Timer1 Gate Single-Pulse mode is first enabled by setting the T1GSPM bit in the T1GCON register. Next, the T1GGO/$\overline{\text{DONE}}$ bit in the T1GCON register must be set. The Timer1 will be fully enabled on the next incrementing edge. On the next trailing edge of the pulse, the T1GGO/$\overline{\text{DONE}}$ bit will automatically be cleared. No other gate events will be allowed to increment Timer1 until the T1GGO/$\overline{\text{DONE}}$ bit is once again set in software. See Figure 17-5 for timing details.

If the Single Pulse Gate mode is disabled by clearing the T1GSPM bit in the T1GCON register, the T1GGO/$\overline{\text{DONE}}$ bit should also be cleared.

Enabling the Toggle mode and the Single-Pulse mode simultaneously will permit both sections to work together. This allows the cycle times on the Timer1 gate source to be measured. See Figure 17-6 for timing details.

17.6.5 TIMER1 GATE VALUE STATUS

When Timer1 gate value status is utilized, it is possible to read the most current level of the gate control value. The value is stored in the T1GVAL bit in the T1GCON register. The T1GVAL bit is valid even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

17.6.6 TIMER1 GATE EVENT INTERRUPT

When Timer1 Gate Event Interrupt is enabled, it is possible to generate an interrupt upon the completion of a gate event. When the falling edge of T1GVAL occurs, the TMR1GIF flag bit in the PIR1 register will be set. If the TMR1GIE bit in the PIE1 register is set, then an interrupt will be recognized.

The TMR1GIF flag bit operates even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

REGISTER 18-3: LCDREF: LCD REFERENCE VOLTAGE CONTROL REGISTER

R/W-0/0	U-0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0
LCDIRE	—	LCDIRI	—	VLCD3PE	VLCD2PE	VLCD1PE	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	C = Only clearable bit

bit 7 **LCDIRE:** LCD Internal Reference Enable bit
1 = Internal LCD Reference is enabled and connected to the Internal Contrast Control circuit
0 = Internal LCD Reference is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5 **LCDIRI:** LCD Internal Reference Ladder Idle Enable bit
Allows the Internal FVR buffer to shut down when the LCD Reference Ladder is in power mode 'B'
1 = When the LCD Reference Ladder is in power mode 'B', the LCD Internal FVR buffer is disabled.
0 = The LCD Internal FVR Buffer ignores the LCD Reference Ladder Power mode.

bit 4 **Unimplemented:** Read as '0'

bit 3 **VLCD3PE:** VLCD3 Pin Enable bit
1 = The VLCD3 pin is connected to the internal bias voltage LCDBIAS3(1)
0 = The VLCD3 pin is not connected

bit 2 **VLCD2PE:** VLCD2 Pin Enable bit
1 = The VLCD2 pin is connected to the internal bias voltage LCDBIAS2(1)
0 = The VLCD2 pin is not connected

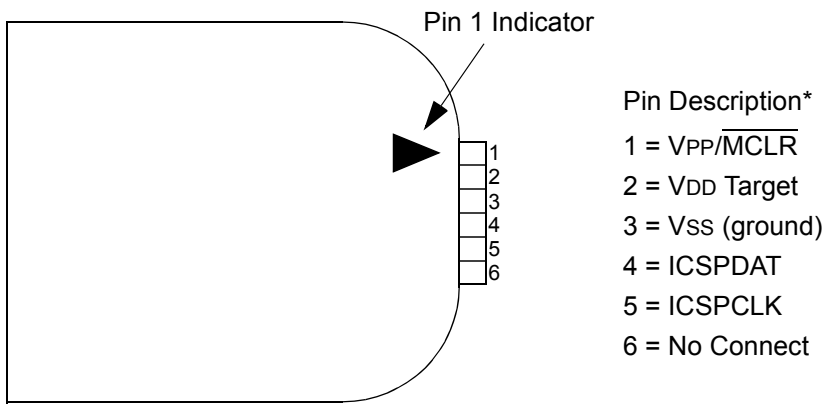
bit 1 **VLCD1PE:** VLCD1 Pin Enable bit
1 = The VLCD1 pin is connected to the internal bias voltage LCDBIAS1(1)
0 = The VLCD1 pin is not connected

bit 0 **Unimplemented:** Read as '0'

Note 1: Normal pin controls of TRISx and ANSELx are unaffected.

Another connector often found in use with the PICkit™ programmers is a standard 6-pin header with 0.1 inch spacing. Refer to Figure 19-2.

FIGURE 19-2: PICkit™ STYLE CONNECTOR INTERFACE



* The 6-pin header (0.100" spacing) accepts 0.025" square pins.

RRF **Rotate Right f through Carry**

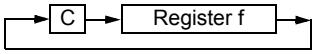
Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.



SLEEP **Enter Sleep mode**

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: The power-down Status bit, $\overline{PD}$ is cleared. Time-out Status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into Sleep mode with the oscillator stopped.

SUBLW **Subtract W from literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (2's complement method) from the 8-bit literal 'k'. The result is placed in the W register.

C = 0	W > k
C = 1	W ≤ k
DC = 0	W<3:0> > k<3:0>
DC = 1	W<3:0> ≤ k<3:0>

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f.

C = 0	W > f
C = 1	W ≤ f
DC = 0	W<3:0> > f<3:0>
DC = 1	W<3:0> ≤ f<3:0>

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) – (W) – ($\overline{B}$) → dest

Status Affected: C, DC, Z

Description: Subtract W and the BORROW flag (CARRY) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

TABLE 21-2: SUPPLY CURRENT (I_{DD})(1,2)

PIC16LF1902/3			Standard Operating Conditions (unless otherwise stated)				
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D010		—	58	75	µA	1.8	F_{OSC} = 1 MHz EC Oscillator mode High-Power mode
		—	115	140	µA	3.0	
		—	133	176	µA	3.6	
D011		—	130	200	µA	1.8	F_{OSC} = 4 MHz EC Oscillator mode High-Power mode
		—	245	300	µA	3.0	
		—	290	350	µA	3.6	
D012		—	218	275	µA	1.8	F_{OSC} = 500 kHz HFINTOSC mode
		—	283	375	µA	3.0	
		—	314	395	µA	3.6	
D013		—	233	325	µA	1.8	F_{OSC} = 1 MHz HFINTOSC mode
		—	309	425	µA	3.0	
		—	347	475	µA	3.6	
D014		—	305	360	µA	1.8	F_{OSC} = 4 MHz HFINTOSC mode
		—	433	520	µA	3.0	
		—	500	600	µA	3.6	
D015		—	395	480	µA	1.8	F_{OSC} = 8 MHz HFINTOSC mode
		—	600	720	µA	3.0	
		—	700	850	µA	3.6	
D016		—	567	670	µA	1.8	F_{OSC} = 16 MHz HFINTOSC mode
		—	915	1100	µA	3.0	
		—	1087	1300	µA	3.6	
D017		—	2.7	7.2	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +125°C
		—	4.5	9.7	µA	3.0	
		—	5.2	12.0	µA	3.6	
D017A		—	2.7	6.5	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +85°C
		—	4.5	9.0	µA	3.0	
		—	5.2	11.0	µA	3.6	
D018		—	2.4	6.7	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +125°C
		—	4.2	9.2	µA	3.0	
		—	4.8	11.5	µA	3.6	
D018A		—	2.4	6.0	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +85°C
		—	4.2	8.5	µA	3.0	
		—	4.8	10.5	µA	3.6	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: FVR and BOR are disabled.

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